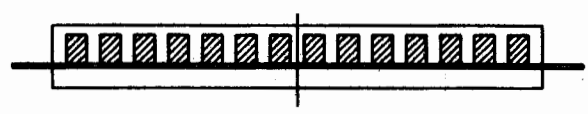


NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.40Ω MAX.



MODIFICATION									
	REDRAWN (CONVERTED CAD DATA) ADDED: SHEET 2/2	CHANGED	DATE	DRAWN	CHECKED	APPROVED			

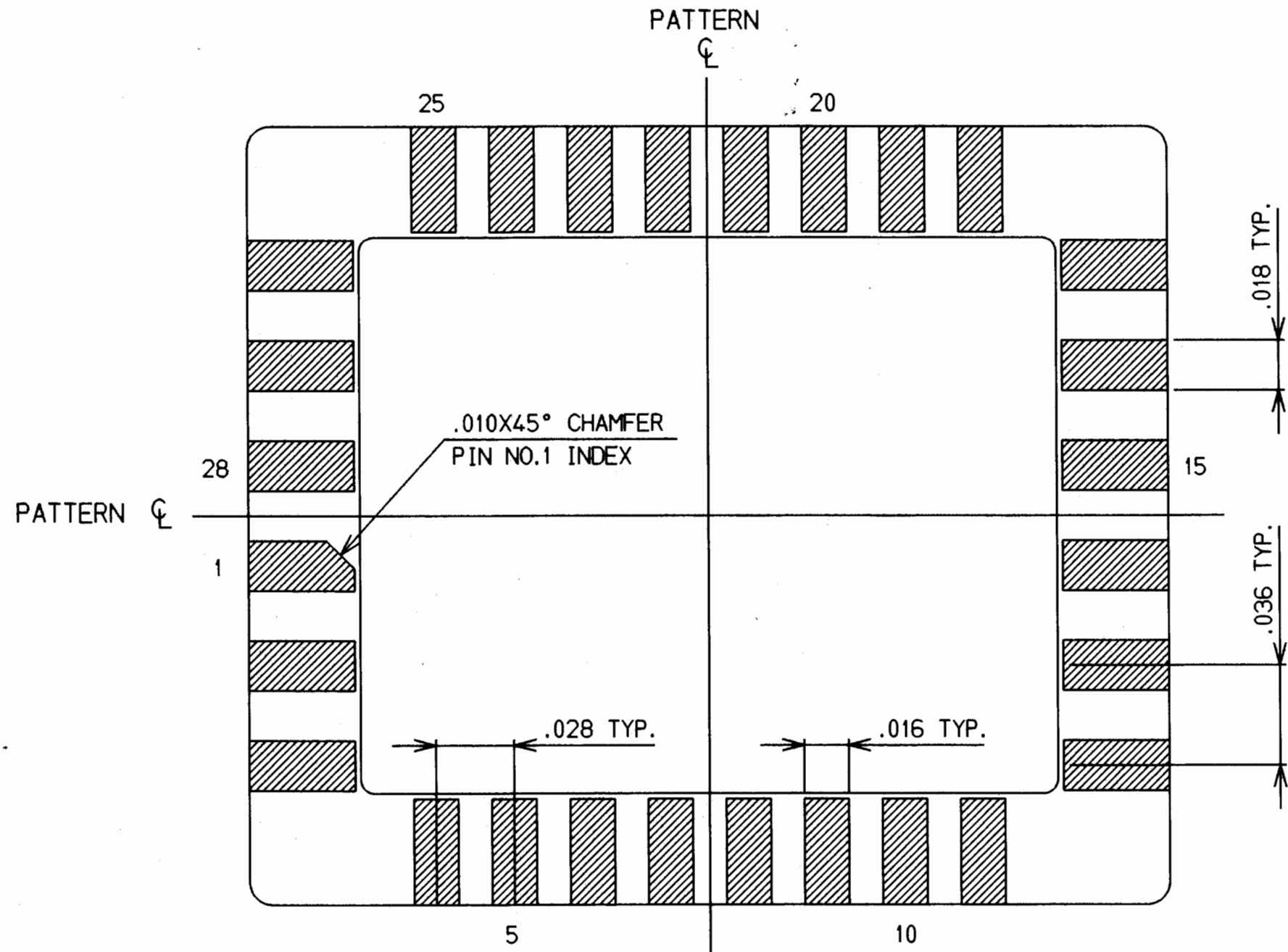
NAME	28 LEAD FLAT PACKAGE
SCALE	5/1
MATERIAL	AS INDICATED


TOLERANCE	±.005
UNLESS OTHERWISE SPECIFIED	
THIRD ANGLE PROJECTION	

FB028W140-1 S=0 D=0			
DRAWN	CHECKED	APPROVED	DATE
S.S	K.K	M.K	FEB.15.89
DRAWING NO. KD-F89140-A			SHEET 1/2



KYOCERA CORPORATION
KYOTO JAPAN



MODIFICATION					NAME	28 LEAD FLAT PACKAGE	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					SCALE	20/1	UNLESS OTHERWISE SPECIFIED	K.I	H.S/S.F	T.A	OCT.27.'94
					MATERIAL		THIRD ANGLE PROJECTION	<i>K. Iryo</i>	<i>H. S. S. F.</i>	<i>T. Atsu</i>	
						KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-F89140-A			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						SHEET